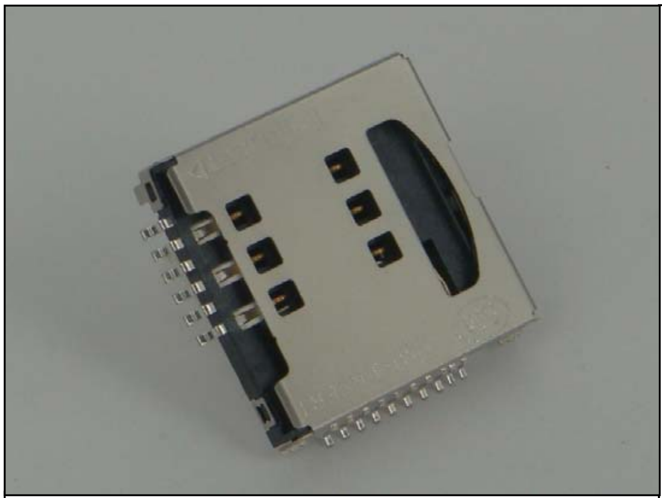
Amphenol

SIM + Micro SD Conn.



Part Number:101-00347-**

SIM + Micro SD Connector

- Push-push eject type
- SMT
- Application for mobile phones

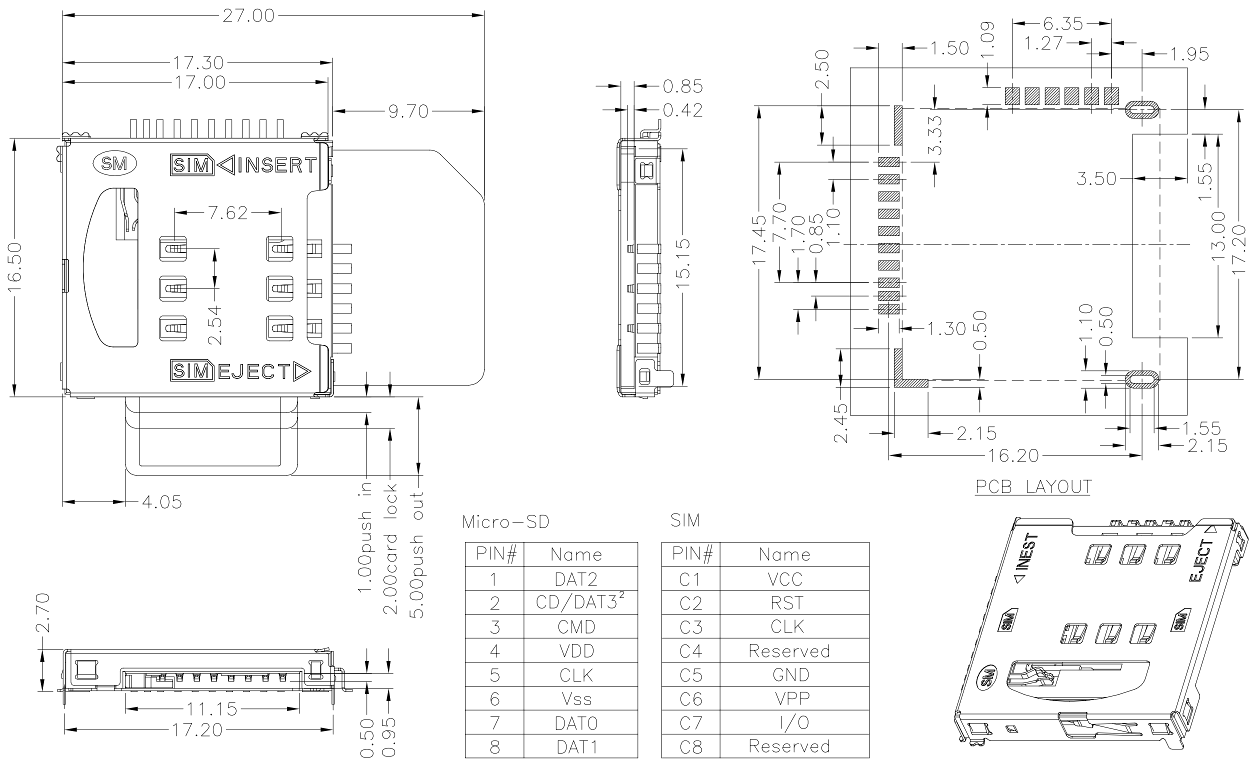
1.Materials:
Housing: High temperature thermoplastic, UL 94V-0 rated.
Contact: Copper alloy
Cover: SUS304 over nickel plating (50U" min)

2.Contact finish:
Selective 1~15u" gold on contact area plating, tin 160u" plating at solder tail, over nickel plating (50u"min)

3.Electrical specifications:
Voltage Rating: 100VAC
Current Rating: 0.5A per contact
Dielectric strength:500VAC initial and 250VAC final for one minute
Insulation Resistance: 1000MΩ min at 500VDC
Contact Resistance: 100mΩ max at 100mA
Operating temperature: -25°C~+70°C

4.Mechanical specifications:
Durability: 5000cycles.
Micro SD Card Mating force: 13.8N max.
Micro SD Card Unmating force: 1N max
SIM Card Mating force: 10N max.
SIM Card Unmating force: 0.3N max

5.RoHS Compliant



Micro-SD

PIN#	Name
1	DAT2
2	CD/DAT3²
3	CMD
4	VDD
5	CLK
6	Vss
7	DAT0
8	DAT1

SIM

PIN#	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved